This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (original): A method of manufacturing a chip-type ceramic electronic component comprising the steps of:

preparing ceramic green sheets having predetermined cutting positions;

coating an inorganic material on a region of each of the ceramic green sheets, inclusive of the predetermined cutting positions;

laminating a predetermined number of the ceramic green sheets to form a ceramic laminated product;

cutting the ceramic laminated product into a chip at the predetermined cutting positions, and sintering the chip to form a ceramic sintered compact; and

forming external electrodes at both ends of the ceramic sintered compact;

wherein the inorganic material includes the same ceramic material as that included in the ceramic green sheets, and an inorganic material having higher resistivity than that of the ceramic material.

Claim 2 (original): The method according to claim 1, wherein the ceramic green sheets are formed from a slurry including an organic binder, a dispersant, a surfactant, an antifoaming agent, a solvent, and a ceramic powder.

Claim 3 (original): The method according to claim 1, wherein the inorganic material is coated in such a manner that the inorganic material is present at ends of each of the ceramic green sheets after the step of cutting.

Claim 4 (original): The method according to claim 1, wherein oxides of at least two metals selected from Mn, Ni, Co, Fe and Cu are used as the ceramic material, and

a metal oxide of Al, Si, Zn, and glass is used as the inorganic material having higher resistivity than that of the ceramic material.

Claim 5 (original): The method according to claim 1, wherein the inorganic material includes a total of 100% by weight of inorganic materials, the content of the same ceramic material as that included in the ceramic green sheets is about 5% to about 50% by weight, and the content of the inorganic material having higher resistivity than that of the ceramic material is preferably about 50% to about 95% by weight.

Claim 6 (original): The method according to claim 1, wherein each of the external electrodes includes an underlying electrode layer and a plated layer.